# ne<mark>x</mark>peria

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Should be replaced with:

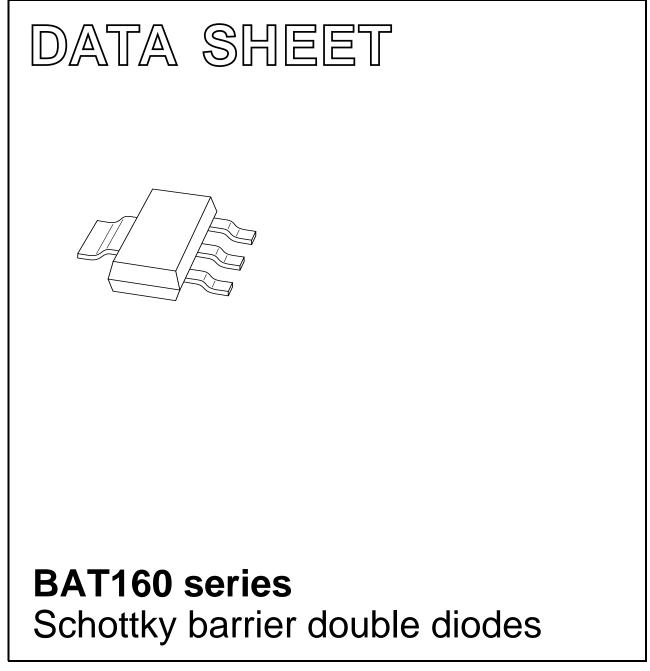
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Kind regards,

Team Nexperia

# DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 1999 Mar 26 1999 Sep 20



## **BAT160 series**

## **FEATURES**

• Low switching losses

NXP Semiconductors

- Capability of absorbing very high surge current
- · Fast recovery time
- · Guard ring protected
- Plastic SMD package.

## APPLICATIONS

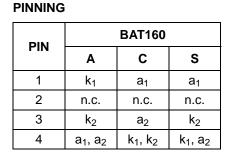
- Low power switched-mode power supplies
- Rectification
- Polarity protection.

## DESCRIPTION

Planar Schottky barrier double diodes encapsulated in a SOT223 plastic SMD package.

#### MARKING

TYPE NUMBER	MARKING CODE
BAT160A	AT160A
BAT160C	AT160C
BAT160S	AT160S



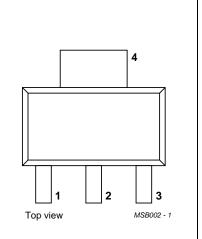


Fig.1 Simplified outline (SOT223) and pin configuration.

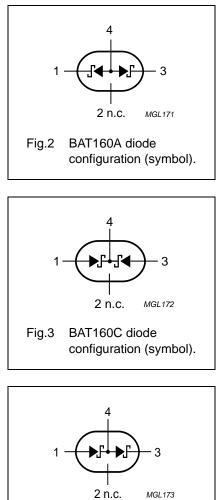


Fig.4 BAT160S diode configuration (symbol).

## BAT160 series

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per diode	Per diode				
V <sub>R</sub>	continuous reverse voltage		-	60	V
l <sub>F</sub>	continuous forward current		-	1	А
I <sub>FSM</sub>	non-repetitive peak forward current	t <sub>p</sub> = 8.3 ms; half sinewave; JEDEC method	-	10	A
I <sub>RSM</sub>	non-repetitive peak reverse current	t <sub>p</sub> = 100 μs	-	0.5	А
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C

## **ELECTRICAL CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
Per diode		· · ·	·	
V <sub>F</sub>	forward voltage	see Fig.5		
		I <sub>F</sub> = 100 mA	400	mV
		I <sub>F</sub> = 1 A	650	mV
		I <sub>F</sub> = 2 A	850	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 60 V; note 1; see Fig.6	350	μA
		V <sub>R</sub> = 60 V; T <sub>j</sub> = 100 °C; note 1; see Fig.6	8	mA
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 4 V; see Fig 7	60	pF

## Note

1. Pulse test:  $t_p = 300 \ \mu s$ ;  $\delta = 0.02$ .

## THERMAL CHARACTERISTICS

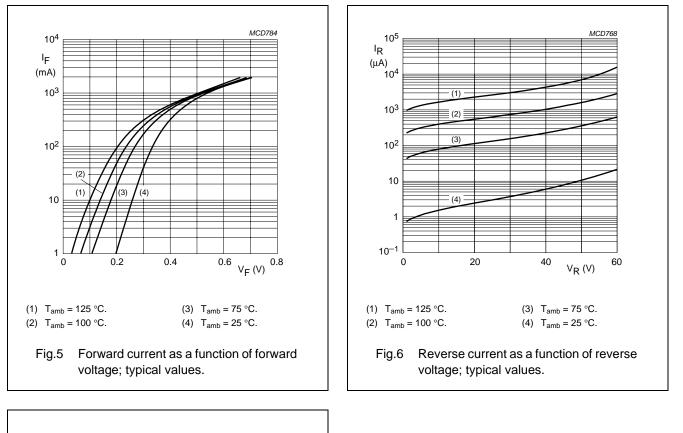
SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	100	K/W

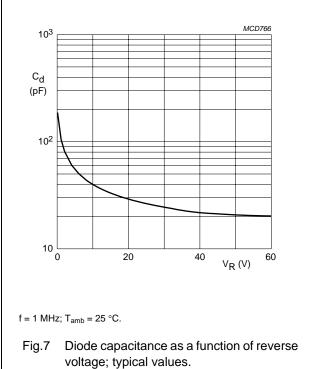
## Note

1. Refer to SOT223 standard mounting conditions.

## BAT160 series

## **GRAPHICAL DATA**



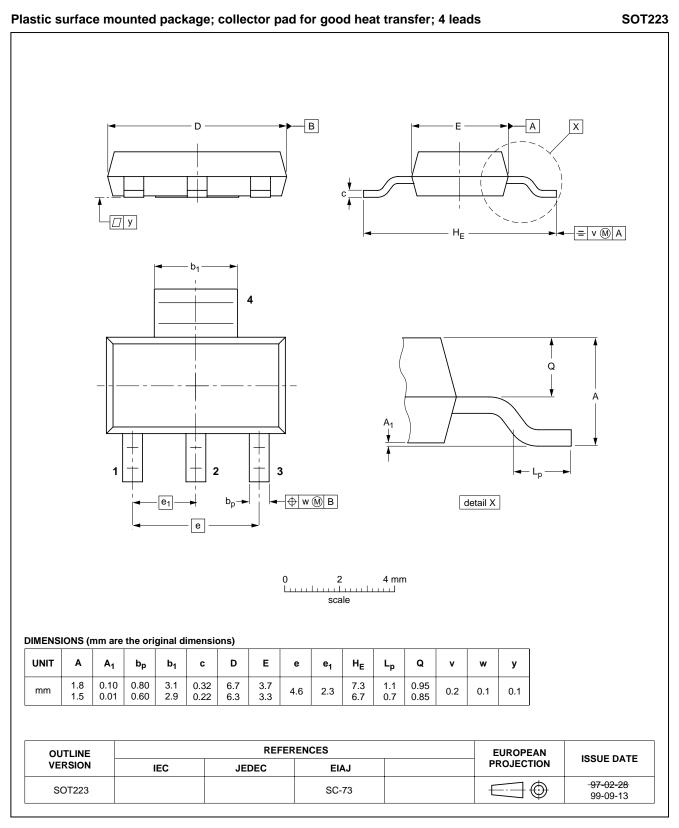


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## BAT160 series

## PACKAGE OUTLINE



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## **BAT160 series**

## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
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# **NXP Semiconductors**

## **Customer notification**

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#### **Contact information**

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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